

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	6 X 6 X 0.75 (4.6 EP)
Lead Count	40
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	5.12E-02	86.2	862000	40.44		404439
Thermosets	Epoxy resin	Proprietary	3.56E-03	6.0	60000	2.82		28151
Thermosets	Phenol resin	Proprietary	3.56E-03	6.0	60000	2.82		28151
Other inorganic materials	Metal Hydroxide	Proprietary	8.90E-04	1.5	15000	0.70		7038
Other inorganic materials	Carbon black	1333-86-4	1.78E-04	0.3	3000	0.14		1408
Subtotal			5.94 E-02	100.00	1000000	46.92		469187

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	5.66 E-02	97.50	975000	44.74		447422
Copper & its alloys	Iron	7439-89-6	1.36 E-03	2.35	23500	1.08		10784
Copper & its alloys	Zinc	7440-66-6	6.97 E-05	0.12	1200	0.06		551
Copper & its alloys	Phosphorus	7723-14-0	1.74 E-05	0.03	300	0.01		138
Subtotal			5.81 E-02	100.00	1000000	45.89		458895

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.94 E-05	100.0	1000000	0.06		627

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	3.02 E-03	100.0	1000000	2.39		23902

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	8.20 E-04	100.0	1000000	0.65		6483

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	4.20 E-03	100.0	1000000	3.32		33198

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.16 E-04	73.40	734000	0.57		5658
Thermoset	Epoxy Resin	Proprietary	1.79 E-04	18.35	183500	0.14		1414
Other organic materials	Metal oxide	Proprietary	2.68 E-05	2.75	27500	0.02		212
Other organic materials	Amine	Proprietary	2.68 E-05	2.75	27500	0.02		212
Other organic materials	Gamma Butyrolactone	Proprietary	2.68 E-05	2.75	27500	0.02		212
Subtotal			9.75 E-04	100.0	1000000	0.77		7708

Package Totals			Weight (g) 1.27 E-01			Percentage (%) 100		PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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